



# Evaluation of fluence dependent variations of capacitance and generation current parameters by transient technique

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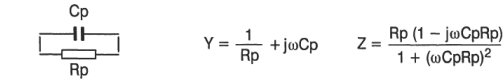
## Outline

- Motivation for alternative techniques vs. impedance based frequency domain one
- Principles of **B**arrier **E**valuation by **L**inearly **I**ncreasing **V**oltage (BELIV) technique
- Fluence dependent BELIV characteristics
- Temperature dependent BELIV characteristics for reverse-biased diodes
- Detector- barrier evaluation summary
- Photo-conductivity gain in heavily irradiated full-depleted detectors
- Summary

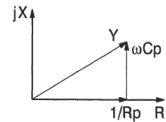
# Motivation for alternative techniques vs. impedance based frequency domain one

## Limitations for impedance, frequency domain based C-V (LRC) techniques

♣ Principle (LCR meter) “works” only if complexity ( $jX_C$ ) appears due to conductance/impedance

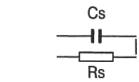


Applicable only when diode can be emulated by the linear elements

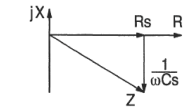


$$D = \frac{1}{\omega C_p R_p}$$

$$C_s = (1 + D^2) \times C_p \quad R_s = \frac{D^2}{1 + D^2} \times R_p$$



$$Z = R_s - j \frac{1}{\omega C_s}$$



$$D = \omega C_s R_s$$

$$C_p = \frac{1}{1 + D^2} \times C_s \quad R_p = \frac{1 + D^2}{D^2} \times R_s$$

$$U_{ac} \ll kT/e$$

$$C_P \approx C_S(U_R) \approx C_{b0} (1 + U/U_{bi})^{-1/2}$$

$$C_{b0} = (e N_D \epsilon \epsilon_0 S^2 / 2e U_{bi})^{1/2}$$

$$U_{bi} = (kT/e) \ln(N_{Ap} + N_D / n_i^2)$$

slope  $C^{-2}$  vs  $U \Rightarrow N_D$ ; intersect.  $U_{bi} - U_F = 0 \Rightarrow U_{bi}$

$$\text{at least } U_{ac}/U_{Rdc} \ll 1$$

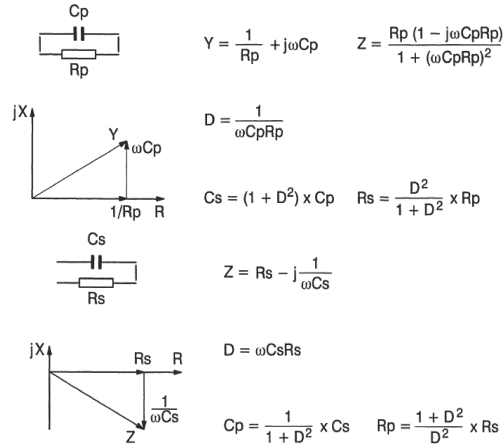
Whether standard paradigm of C-V technique is valid when diode current  $i_C \approx i_{gen}, i_{capt}$  for  $U_R$  -?

### LRC phasor

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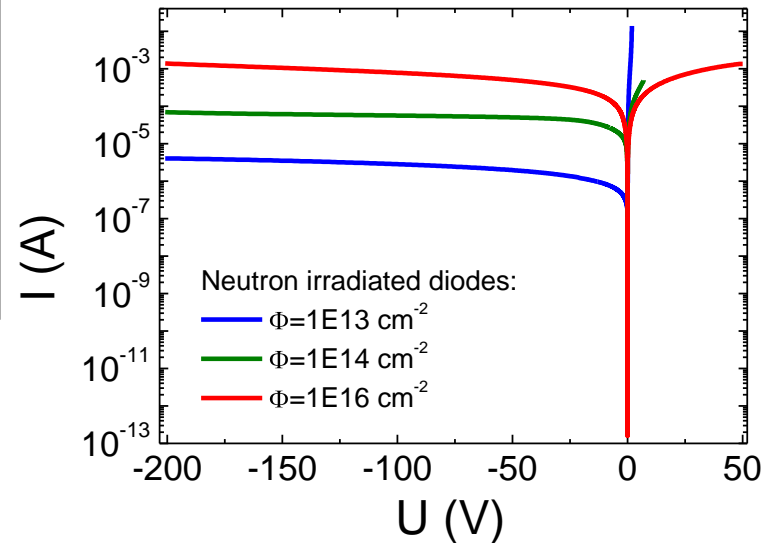
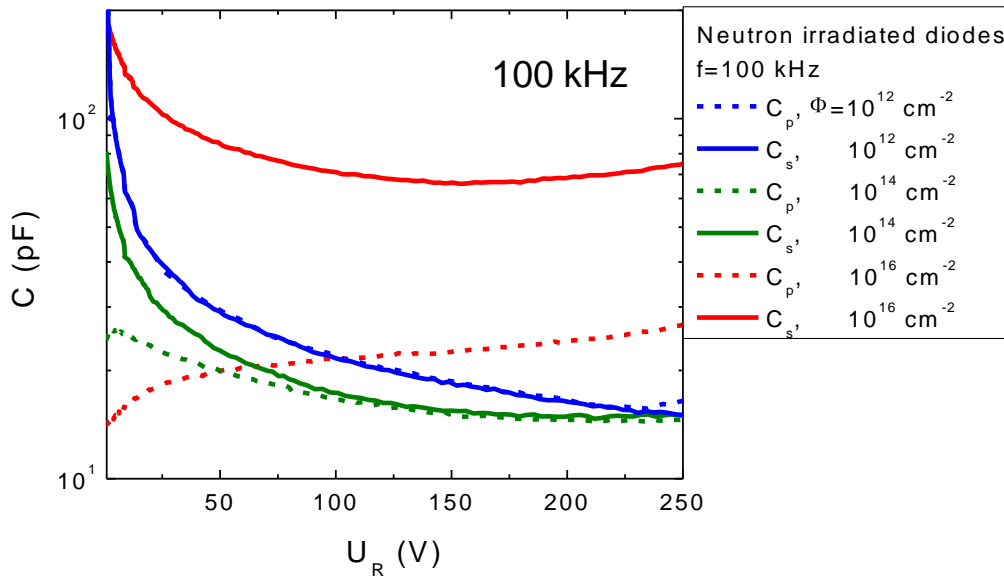
$$U_{bi} = (kT/e) \ln(N_{A+} N_D / n_i^2)$$

$$\text{at least } U_{ac}/U_{Rdc} \ll 1$$

Whether standard paradigm of C-V technique is valid when diode current  $i_C \approx i_{gen}, i_{capt}$  & how to correlate with I-V -?

LRC phasor

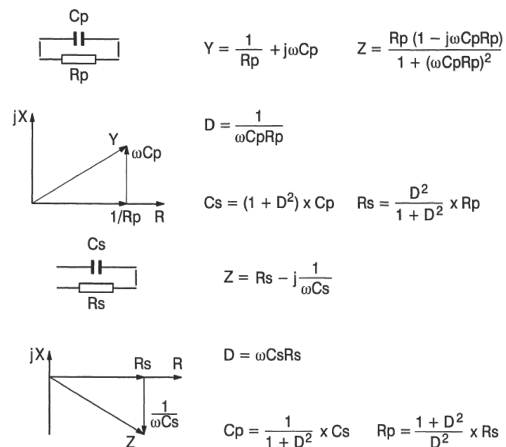
Why huge difference in  $C_p$  and  $C_s$  appears for heavily irradiated diode -?  
 Why C-V measurements are improved at high frequencies -?  
 Why extracted depletion voltage depends on frequency -?



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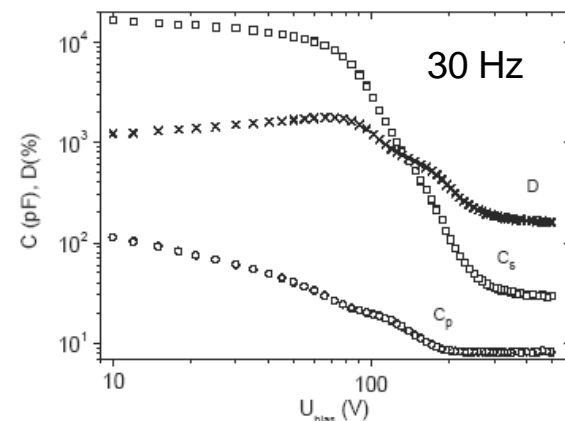
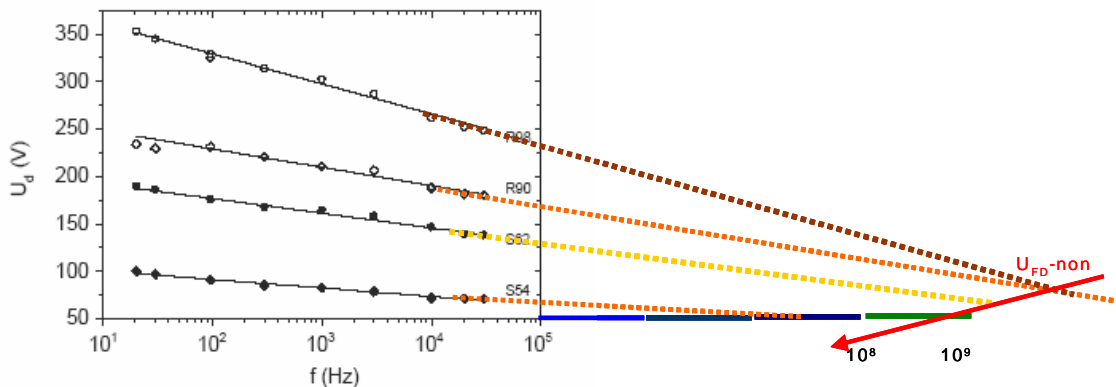
$$C_{b0} = (eN_D \epsilon \epsilon_0 S^2 / 2eU_{bi})^{1/2}$$

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### LRC phasor

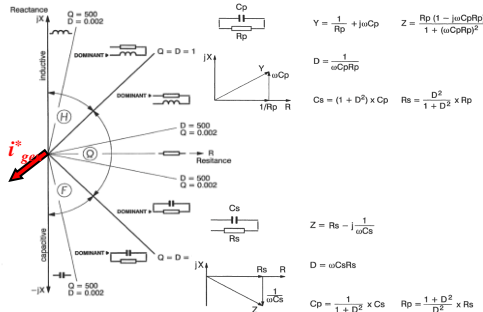
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# Motivation for alternative techniques vs. impedance based frequency domain one

## Limitations for impedance, frequency domain based C-V (LRC) techniques

♣ Principle (LRC meter) “works” only if complexity ( $jX_C$ ) appears due to impedance



How are the generation and carrier capture currents included into standard C-V for (heavily) irradiated pin diodes-? with large  $i_{gen} = en_i w(U) S / \tau_{gen}$

$\tau_{gen} = 2 \cosh(E_L - E_i) / V_T \sigma N_L$  - short  
 $i_{\Sigma} = i_C + (i_{gen} + i_{diff})$  - complex quatn.)

$I_{gen,capt} = en_i w(U) S / \tau_{gen,capt}$  becomes a complex quantity for ac  $U_{\sim}$   
 Is it possible to separate an impact of  $i_{gen,capt}$  from C-V to correlate with I-V-?

LRC phasor becomes multi-dimensional

### Indications that LRC impedance principle and a paradigm of parameter extraction does not work anymore:

- appears huge difference between  $C_P$  and  $C_S$  - artefact of principle due to  $i_{gen}^*$
- impossible to separate  $i_C$  and  $i_{gen}^*$
- appears crucial reverse voltage drop:
  - e.g.  $U_{gen} = i_{gen} R_{depl} = w^2(U) / \mu \tau_{gen}$  and indefinite voltage drop (on junction and within bulk)  $U_{techn} = U_{gen}$
  - $U_{FD}$  shifts crucially to the high voltage/high frequency range due to increase of  $U_{gen}$  with  $U_{ext}$
- depletion width becomes indefinite (un-known  $\tau_{gen}$ )
  - estimation by iteration procedure-- simulations by TCAD/SPICE or approach of positive root  $w(U_{ex}) = [2 \epsilon \epsilon_0 (U_{bi} + U_{ext}) / \{e N_D (1 + 2 \epsilon \epsilon_0 / e N_D \mu \tau_{gen})\}]^{1/2}$  - valid for  $U_{ac} / U_{dc} \ll 1$ ; necessary additional parameters)
- intricate ( $w(U_{ext})$ ) dependence on frequency, temperature, voltage - due to  $\tau_{gen}$
- appears an artificial effective doping  $N_{ef}^{art} = N_D (1 \pm 2 \epsilon \epsilon_0 / e N_D \mu \tau_{gen})$  - seeming variations

### ♣ Technical limitations for LRC-meters based measurements

- necessary to make measurements in the range of low  $U_R$  voltages to avoid the impact of  $i_{gen} \sim U^{1/2}$  - LRC meters with small ac voltage  $U_{\sim} \ll kT/e$
- dc and ac voltage sources connected in series (dependence on  $R_{in\ dc}$ ),
- noise ( $U_{ns}$ ) suppressed dc voltage sources due to small  $U_{ns} \ll U_{\sim}$ ,
- no additional loops (capacitors, resistors), limitations to ground for LRC-meters with wide range of external dc voltages

# Motivation for alternative techniques vs. impedance based frequency domain one

## ♣ Principles to include $i_{gen, capt}$

- To include dominant physical processes, analysis of  $C_{bj}(U) = \varepsilon\varepsilon_0 S/w(U)$  is an alternative way with *estimation of  $w(U)$  by iteration procedure- approach of positive  $w(U)$  root using  $U_{gen} = w^2/\mu\tau_{gen, capt}$*

$$w(U_{R,ext}) = \sqrt{\frac{2\varepsilon\varepsilon_0 (U_{bi} + U_{R,ext} \pm U_{gen, capt})}{eN_D}} \cong \sqrt{\frac{2\varepsilon\varepsilon_0 (U_{bi} + U_{R,ext})}{eN_D \left(1 \pm \frac{2\varepsilon\varepsilon_0}{eN_D \mu\tau_{gen, capt}}\right)}}$$

valid for  $U_{ac}/U_{dc} \ll 1$  and leads to different  $N_{eff} = N_D (1 \pm 2\varepsilon\varepsilon_0 / eN_D \mu\tau_{gen, capt})$  for  $\omega \approx 1/\tau_{gen}$  (+) and for  $\omega \approx 1/\tau_{capt}$  (-)

- Evaluation of  $w(U_{junct})$  by simulations by TCAD/SPICE etc.**

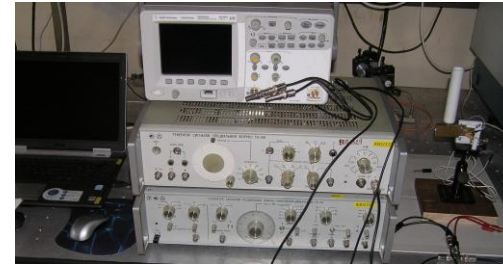
$$i_{\Sigma}(U) = i_C[w(U)] + \frac{en_i w(U) S}{\tau_{gen, capt}}$$

## ♣ Alternative measurement techniques capable to separate components

## BELIV technique

$$U(t) = U_p / \tau_{PL} t = At$$

$$\text{LIV ramp } A = U_p / \tau_{PL} = \partial U / \partial t$$



LIV always starts from  $U(t)=0$



AT-DSO-6102A

$i_c$

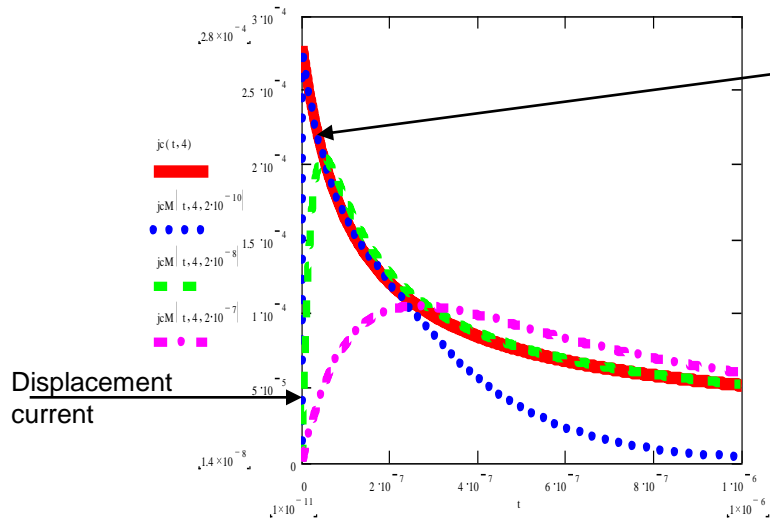
$$\tau_{PL} = 10 \text{ ns} \Rightarrow 500 \text{ } \mu\text{s}$$

$$U_p = 0.01 \Rightarrow 5 \text{ V}$$

$$C_b = 2 \text{ pF} \Rightarrow 40 \text{ } \mu\text{F} \text{ with resolution } \sim 0.2 \text{ pF} \mid (2\text{-}20 \text{ pF})$$

$$U_c = i_c \cdot 50 \text{ } \Omega = 10 \text{ mV} \Rightarrow 4 \text{ pF} \mid A = 5 \cdot E8 \text{ V/s}$$

# BELIV technique, model and simulations



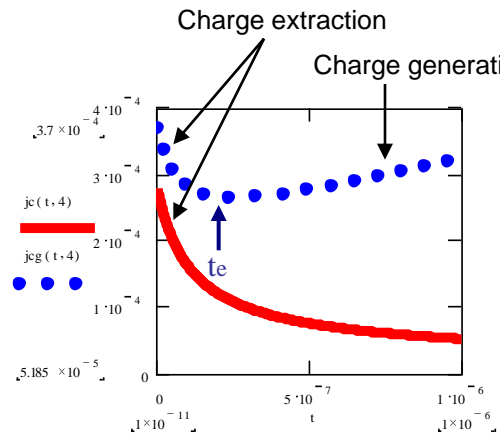
Charge extraction current

## Reverse bias

$$i_C(t) = \frac{dq}{dt} = \frac{\partial U}{\partial t} (C_b + U \frac{\partial C_b}{\partial U}) = AC_{b0} \frac{1 + \frac{At}{2U_{bi}}}{(1 + \frac{At}{U_{bi}})^{3/2}}$$

$$i_{CM}(t) = \frac{1}{\tau_{RC}} \int_0^t i_C(x) \exp[-\frac{(t-x)}{\tau_{RC}}] dx$$

Short transient processes acting in series due to  $t_D, \tau_{DR}, \tau_{capt}, \tau_{gen}$  etc (to complete a circuit) determine a delay, - reduction of the initial displacement current step. Similar effect perturbs the C-V characteristic at  $U_R \rightarrow 0$  measured by impedance technique (LRC-meters).



$$i_{R\Sigma}(t) = i_C(t) + i_{diff}(t) + i_g(t) = AC_{b0} \frac{1 + \frac{At}{2U_{bi}}}{(1 + \frac{At}{U_{bi}})^{3/2}} + i_{diff\infty} (1 - e^{-\frac{eAt}{kBT}}) + \frac{en_i S w_0}{\tau_g} (1 + \frac{At}{U_{bi}})^{1/2}$$

$$t_e = \frac{U_{bi}}{A i_g(0)} \left[ \frac{i_C(0)}{4} - i_g(0) + \sqrt{\left(\frac{i_C(0)}{4}\right)^2 + \frac{3}{2} i_C(0) i_g(0)} \right]$$



## BELIV technique $U_F$ model

$$U(t) = U_P / \tau_{PL} t = At$$

Forward bias

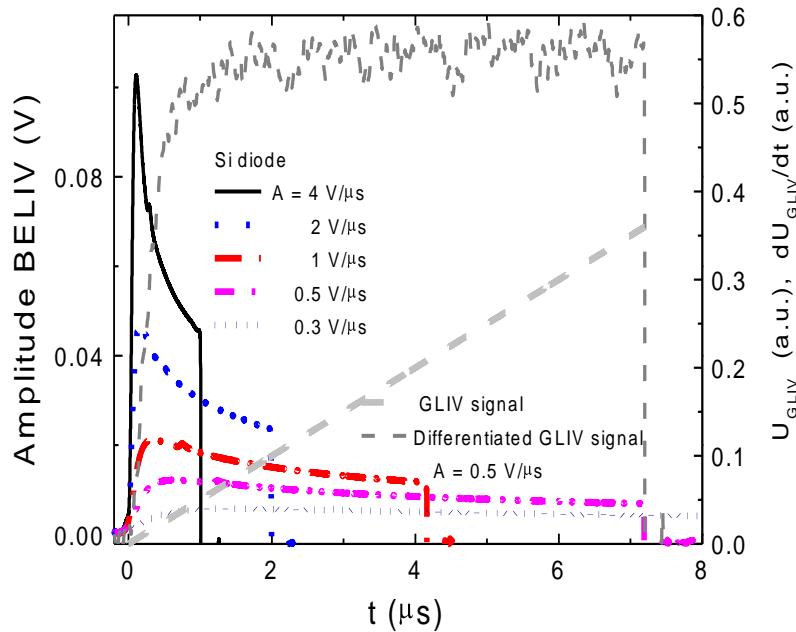
$$U_F(t) = At - R_L i_{\Sigma F}(t),$$

$$i_{\Sigma F}(t) = i_{CF}(t) + i_{Cdiff}(t) + i_R(t) + i_{diff}(t) =$$
$$\frac{\partial U_F(t)}{\partial t} \left\{ C_{b0} \frac{(1 - \frac{U_F(t)}{2U_{bi}})}{(1 - \frac{U_F(t)}{U_{bi}})^{3/2}} + C_{diff0} \left[ 1 + \frac{eU_F(t)}{k_B T} \right] e^{\frac{eU_F(t)}{k_B T}} \right\} + \frac{en_i w_0}{2\tau_R} \left( 1 + \frac{U_F(t)}{U_{bi}} \right)^{1/2} + i_{diff\infty} (e^{U_F(t)/k_B T} - 1)$$

Transcendental, iterative simulations

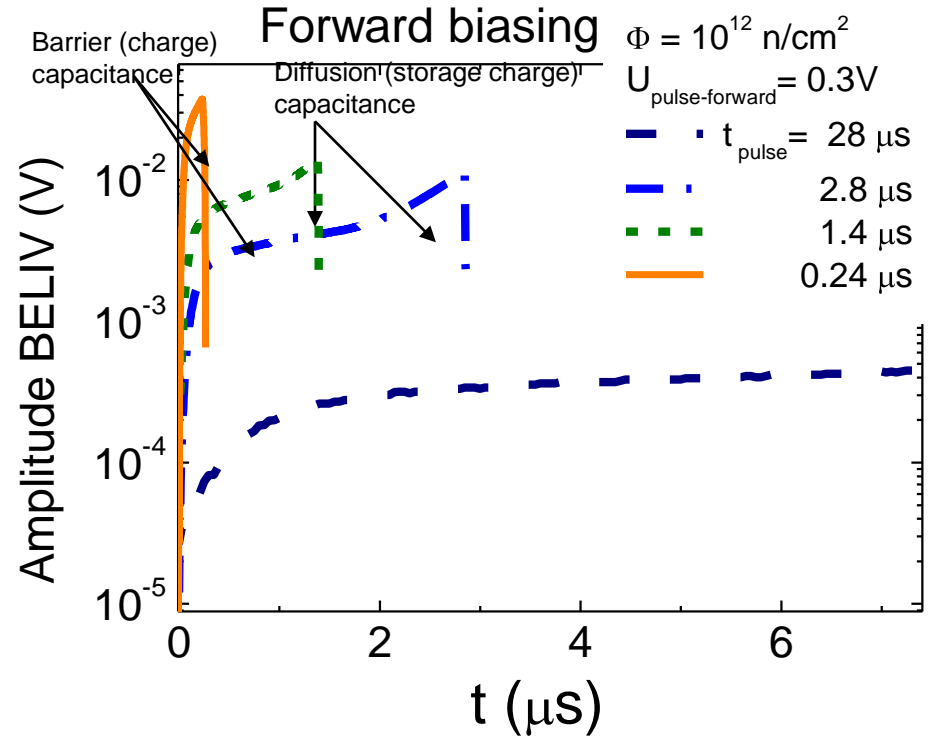
# BELIV transients – measurement technique

## Reverse biasing



a

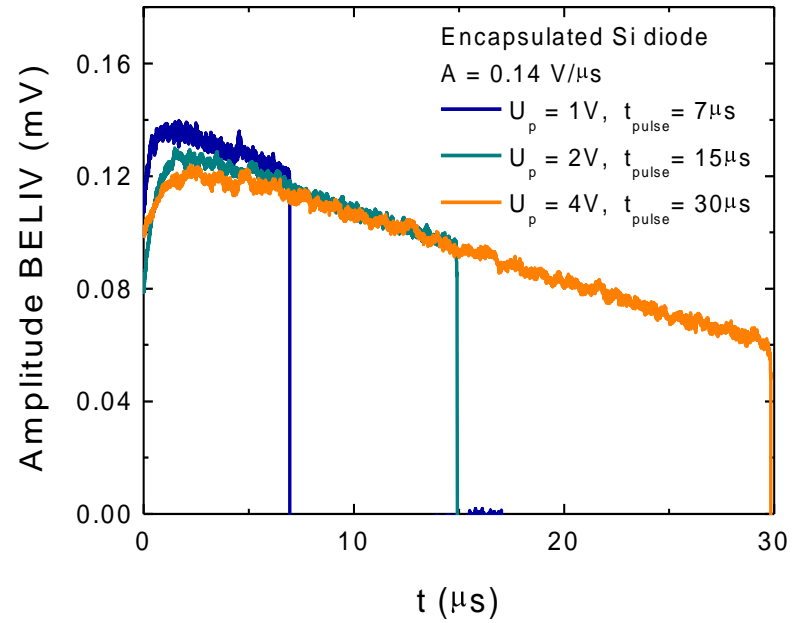
a- **Barrier evaluation** by linearly increasing voltage (BELIV) technique based on charge extraction current transients measured in the non-irradiated and irradiated with small fluence pin diode at reverse ( $U_R$ ) biasing by LIV pulses.



b

b- Charge injection BELIV transients for forward ( $U_F$ ) biased pin diode irradiated with small fluence varying ramp  $A$  of LIV pulses.

## BELIV transients – measurement technique

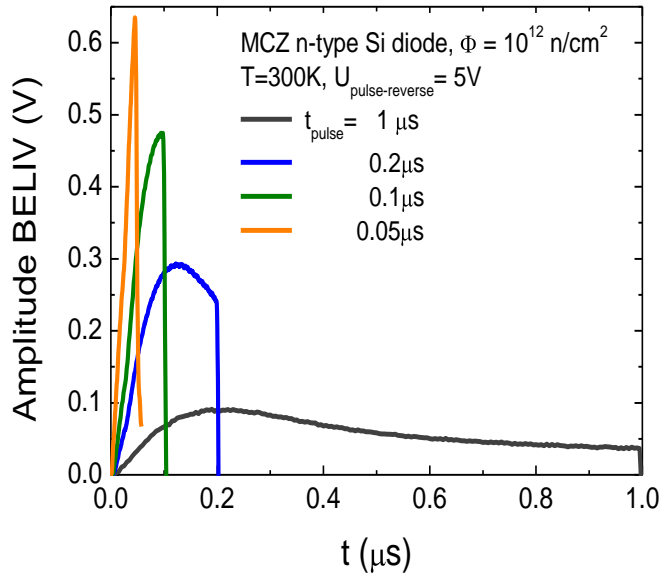


$U_R$  pulse duration dependent BELIV transients at a constant LIV ramp is equivalent to  $C_b - V \sim t$

# BELIV transients on WODEAN pad-detectors neutron-irradiated with fluences $10^{12}$ - $10^{16}$ n/cm<sup>2</sup>

## Reverse bias

Barrier capacitance prevails for short LIV pulses

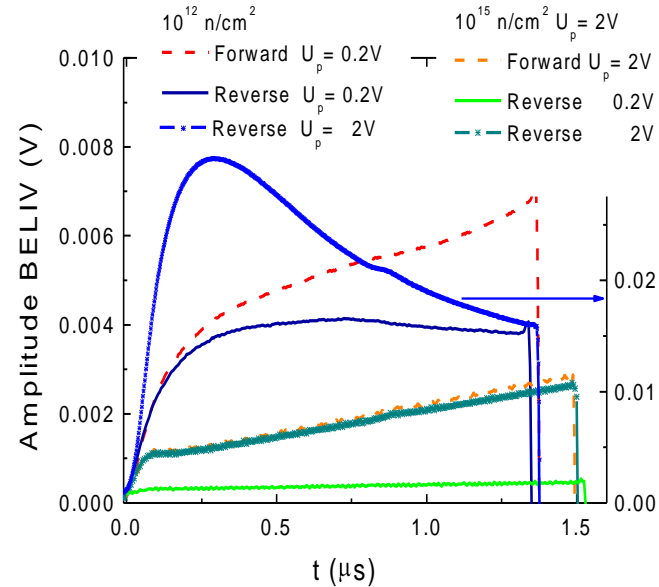


a

## Reverse & Forward bias

$C_b$  dominates for  $1E12$  n/cm<sup>2</sup>

$I_{gen}$  &  $i_{rec}$  dominate for  $1E16$  n/cm<sup>2</sup>



b

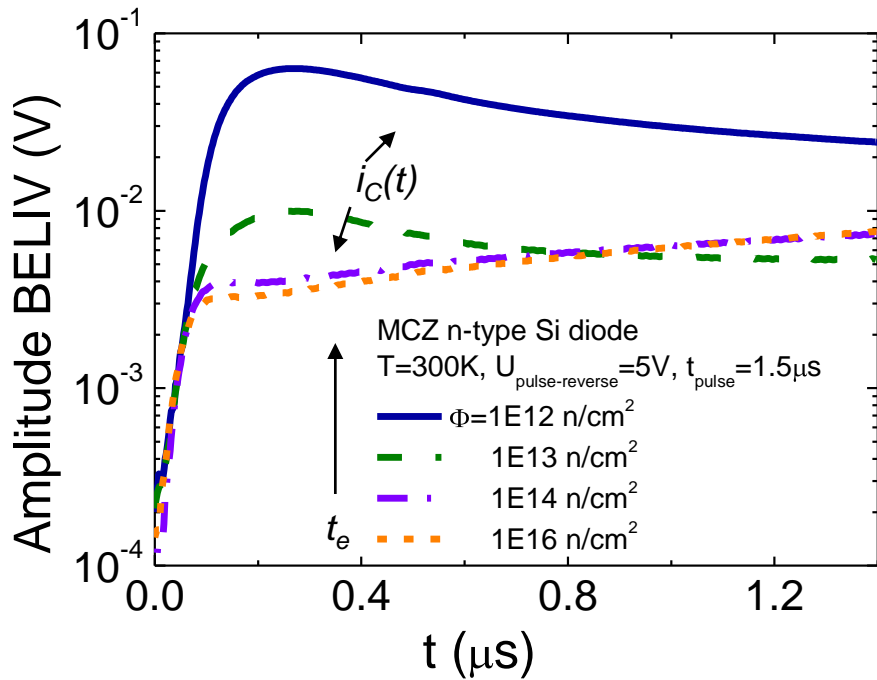
a- LIV pulse duration (LIV ramp) dependent BELIV transients at reverse ( $U_R$ ) bias. b- Comparison of charge extraction ( $U_R$ ) and injection ( $U_F$ ) BELIV transients measured on diodes irradiated by neutrons of different fluence.

To separate the displacement, generation/capture and diffusion currents, a wide range of duration/voltage and perfect LIV pulses are necessary.

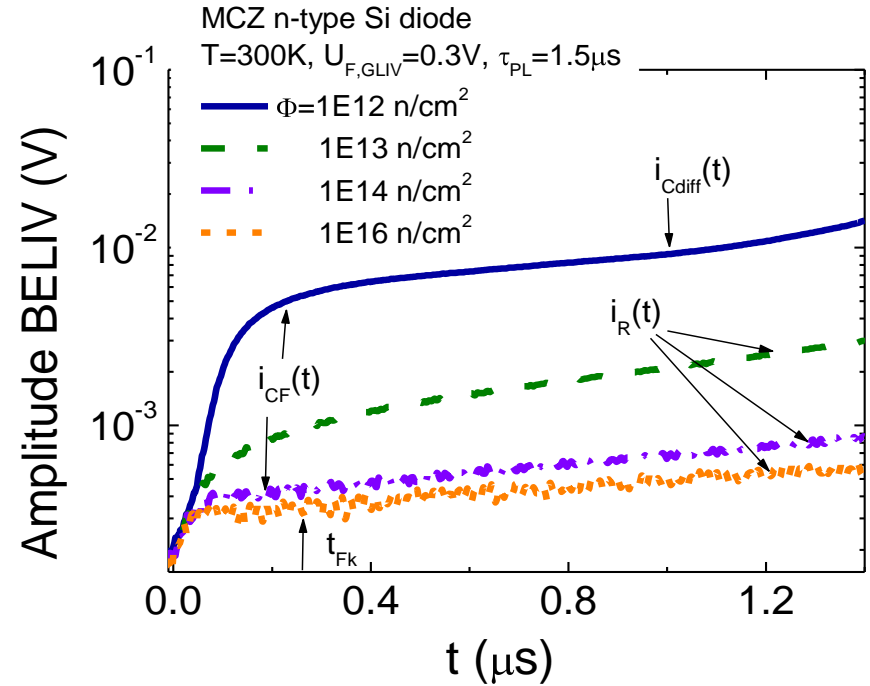
For diodes irradiated with rather small fluence charge extraction current prevails for Rev biasing, while charge storage (diffusion) capacitance dominates for Frw biased diodes.

In heavily irradiated material generation and recombination currents dominate. Voltage on junction is governed by  $U_{jnc} = At - i\Sigma RL$

# BELIV results –dependence on fluence



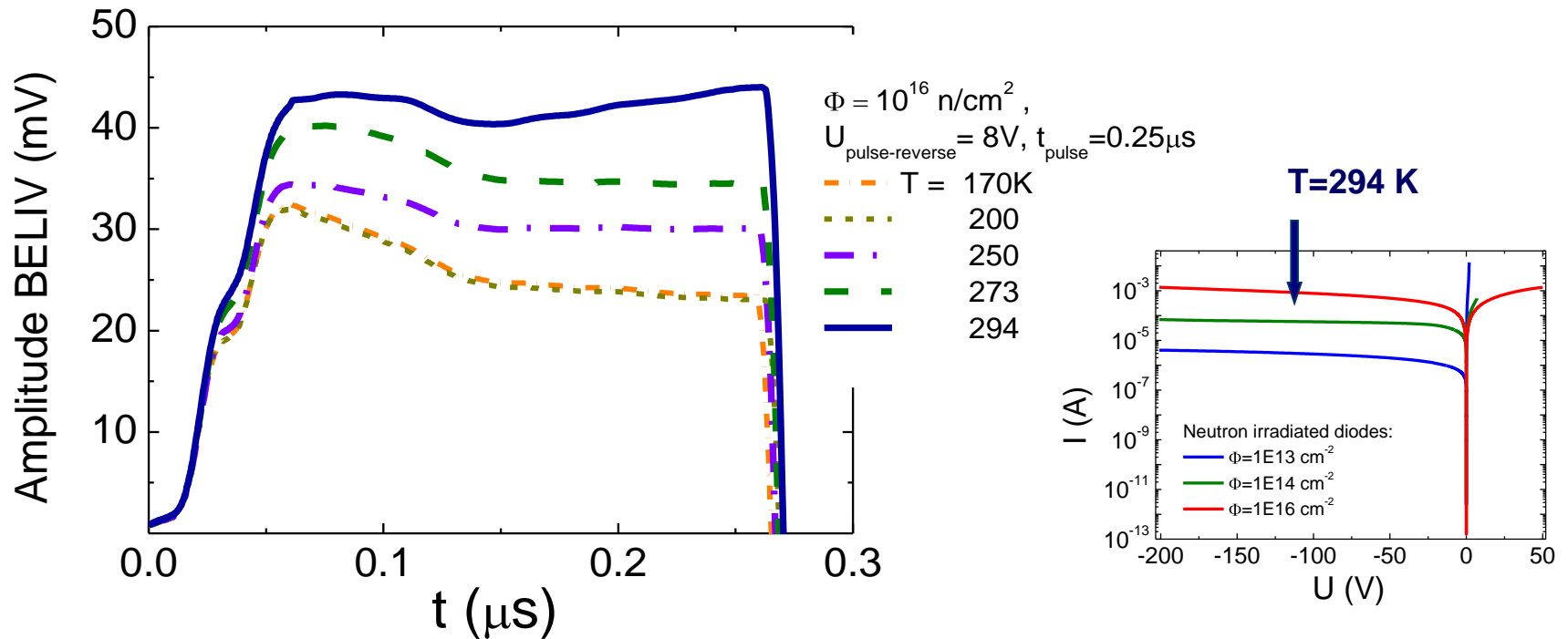
a



b

a- Variations of BELIV transients with irradiation fluence for reverse biased Si pin pad-detector at the same LIV parameters ( $A= 3\text{ MV/s}$ ,  $\tau_{PL} = 1.5\ \mu\text{s}$ ). b- Injection current BELIV transients for different fluence neutron irradiated Si pin diodes. The extreme points ( $t_e$ ,  $t_{FK}$ ) are denoted on transients.

## BELIV results –dependence on temperature

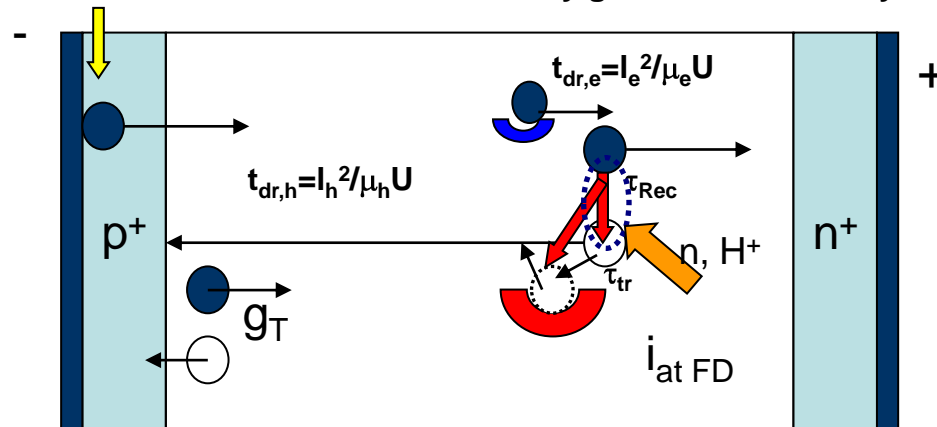


Temperature dependent variations of BELIV transients in heavily (with fluence of  $10^{16} \text{ n/cm}^2$ ) irradiated Si pin diode.

***$U_{bi}$  still exists (for  $1\text{E}16 \text{ n/cm}^2$ ) but diode at RT resembles a photo-resistor at large  $U_{bias}$***

# Photo-conductivity gain (PCG)

for  $t_{dr,e} < t_{dr,h}$  to keep el. neutrality additional carrier(s) is injected from electrode or thermally generated in vicinity of electrode



$$PCG = t_{dr,h} / t_{dr,e} \Rightarrow CCE > 1 \text{ if } t_{dr,e} < t_{dr,h} < \tau_{Rec}$$

$$CCE \Rightarrow 0 \text{ for } \tau_{Rec} < t_{dr}$$

- radiation induced generation (trapping) centers (*increased density with fluence*) enhance probability for PCG processes;
- reduction of  $t_{dr}$  by enhancement of  $U > U_{FD}$  and by reduction of  $d \sim I_h$ ;
- resolvable PCG pulses if time gap  $t_{ar}$  between arrival of HE particles  $t_{ar} > \tau_{tr}$

## Summary: detector- barrier evaluation by LIV

For barrier evaluation better to control  $U_{bi}=(kT/e)\ln(N_A N_D/n_i^2)$

BELIV shows  $N_D$  is invariable, barrier exists, detector functional, but necessary to shift the operational range towards high ( $\omega$ ) frequency/short time domain range, to decrease bias voltage (to suppress  $i_{gen}$ ) etc.

Optimization of the detector' functionality is possible only by a trade-off among desirable parameters:

- necessity to shift the time domain  $\tau_{TD}$  towards short shaping time  $\tau_{TD}\approx 1/\omega$  is compatible with LHC operation regime, but, to reduce an impact of  $i_{gen, rec}$ , it is desirable to keep  $\tau_{rec,gen} > \tau_{TD} > \tau_{DR}$   
(reduction of  $\tau_{DR}$  is possible by enhancement of doping);
- to suppress  $i_{gen, rec}$  - reduction of the operational voltages, temperature and base thickness  $d$ ;
- to reach full-depletion – enhancement of operational voltage, but increases a problem with  $i_{gen}\sim U^{1/2}$  ;
- to reduce impact of g-r noises – enhancement of detector volume  $V=Sd$  through base thickness or area  $S$  ( $\Rightarrow$  3-D detectors);
- to approach a photo-conductivity gain regime (to increase CCE) enhancement of operational voltage and proper reduction of base thickness  $d$ ;

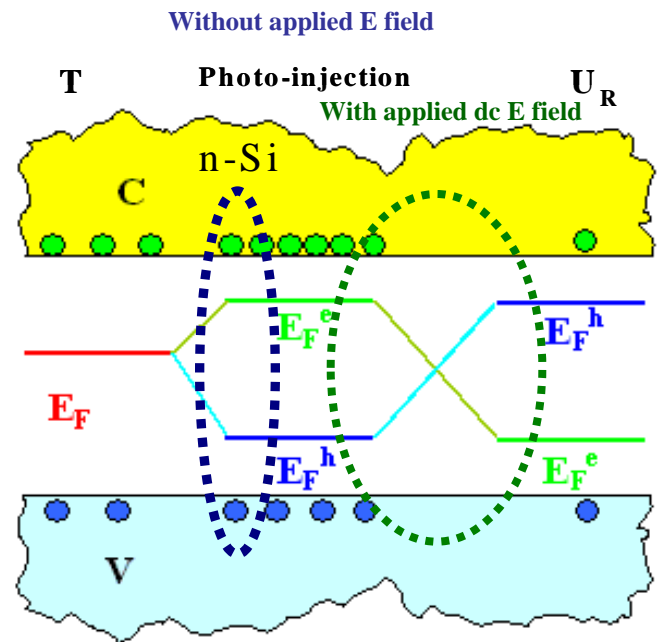


## Summary

- **Validity of a simple paradigm (standard C-V method) of the parameter extraction from C-V characteristics in irradiated diodes should be verified for every experimental regime and adjusted by selecting  $\omega$ ,  $U_R$ ,  $U_{ad}$ ,  $T$  parameters**
- **Developed BELIV transient technique enables one to control variations of  $U_{bi}$  and generation current dependent on fluence and temperature. Increase of generation current for reverse biased diode and reduction of diffusion capacitance/current due to recombination of injected carriers in forward biased diodes leads to the symmetric (*Rev/Frw*) I-V/C-V transient characteristics. Symmetry of these characteristics indicate the dominant mid-gap centers/clusters with pinned  $E_p$**
- **BELIV shows  $U_{bi}$  and  $N_D$  is invariable and detector is functional, while in heavily irradiated detectors for  $20 \text{ Hz} < \omega < 10 \text{ MHz}$  deterioration of characteristics is determined by  $\tau_{capt,gen}$**
- **Optimization of the detector' functionality is possible only by a trade-off among desirable parameters. CCE can be increased through proper design of detector (d) and applied detection regimes ( $U$ ,  $\tau_{response}$ ) to reach PCG.**

Thank You for attention!

# Trivial remarks concerning SRH relations between recombination – generation lifetime

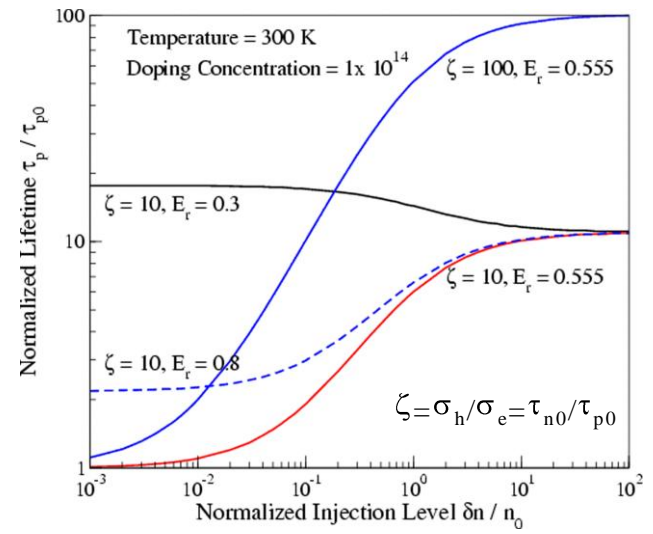
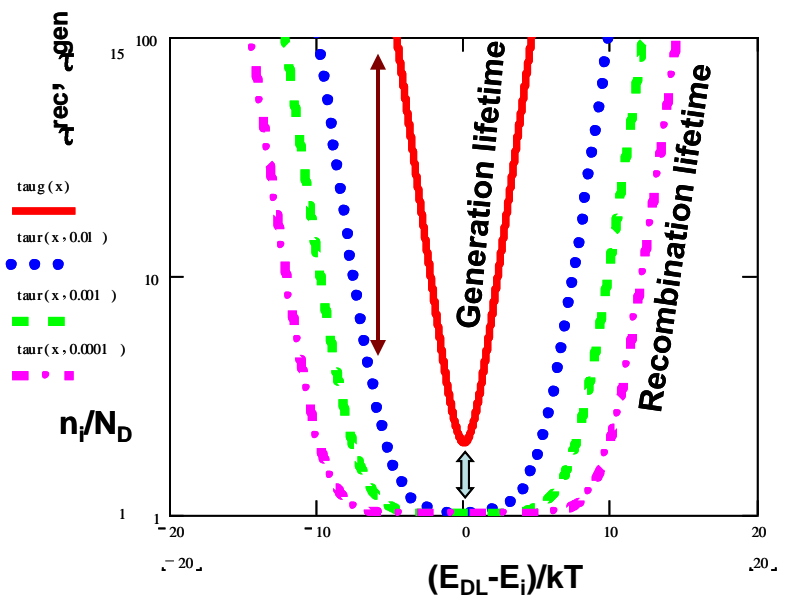


$$n^e \cdot p^e - n_i^2 = 0 \quad R > 0 \quad n^e \cdot p^e < n_i^2$$

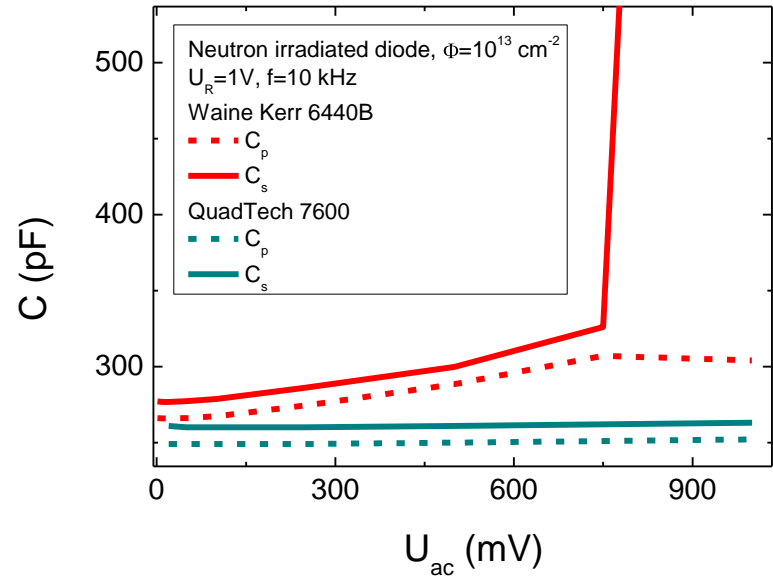
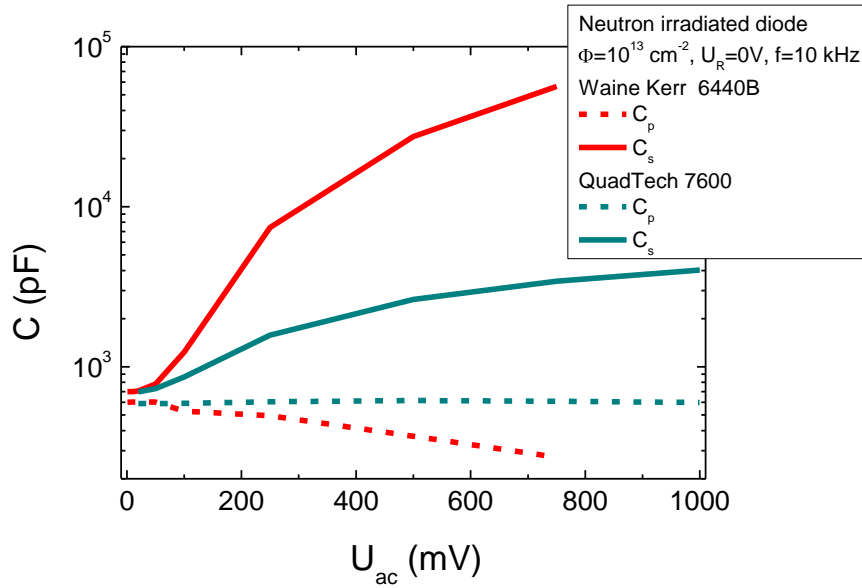
$$\text{Eqv.} \quad n^e p^e > n_i^2 \quad G < 0$$

$$\tau_{rec} = \frac{\Delta n}{R} = \frac{1}{v_0 N_{DL}} \left[ 1 + \frac{2n_i}{n^e} \cosh\left(\frac{E_{DL} - E_i}{kT}\right) \right] \Big|_{n^e \gg n_i} = \frac{1}{v_0 N_{DL}}$$

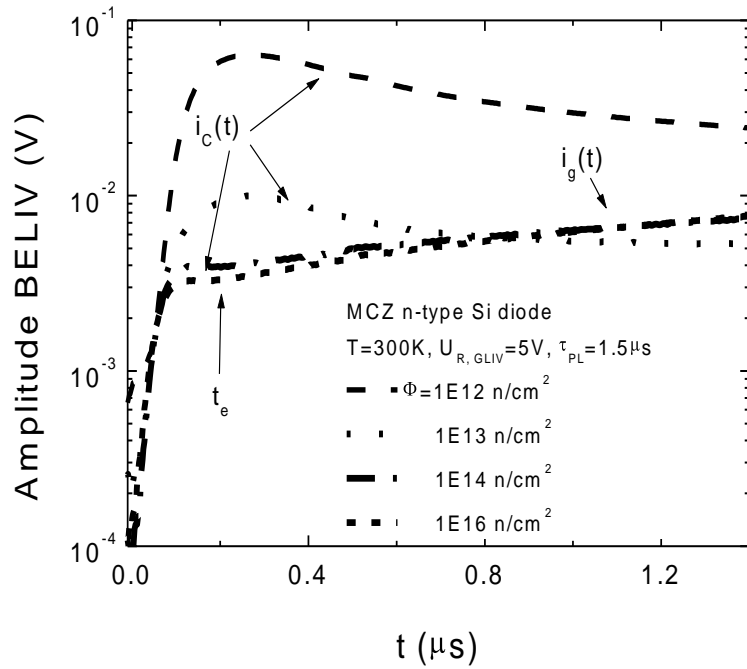
$$\tau_{gen} = n_i / G = \frac{2 \cosh\left(\frac{E_{DL} - E_i}{kT}\right)}{v_0 N_{DL}}$$



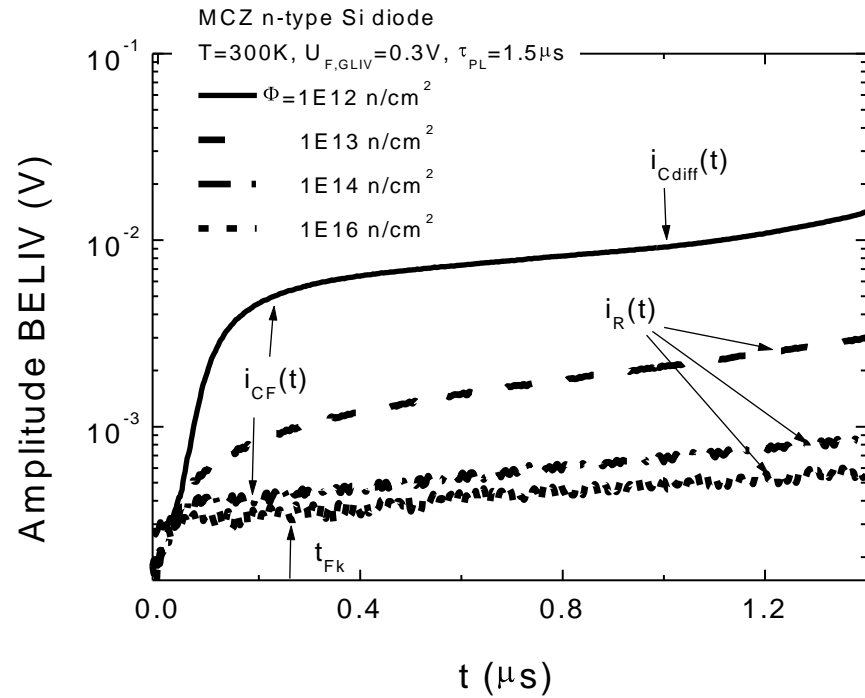
# Calibration of LRC-meters



# BELIV results –dependence on fluence



a



b

a- Variations of BELIV transients with irradiation fluence for reverse biased Si pin pad-detector at the same LIV parameters ( $A= 3\text{ MV/s}$ ,  $\tau_{PL} =1.5\ \mu\text{s}$ ). b- Injection current BELIV transients for different fluence neutron irradiated Si pin diodes. The extreme points ( $t_e$ ,  $t_{Fk}$ ) are denoted on transients.

# Relation among $C_{b,,}$ , $R_{depl}$ and LRC: $Y, R_p, C_p$

$$p_n(x) = p_{n0} \left[ \exp \frac{eU}{kT} - 1 \right] e^{-\frac{x}{L_p}} \quad U = U_0 + U_a e^{i\omega t}$$

$$p_n(x)|_{U_0} = p_{n0} \left[ \exp \frac{eU_0}{kT} - 1 \right] e^{-\frac{x}{L_p}}$$

$$p_n(x)|_{U_0 + U_a e^{i\omega t}} = p_{n0} \left[ \exp \frac{e(U_0 + U_a e^{i\omega t})}{kT} - 1 \right] e^{-\frac{x}{L_p}}$$

$$\Delta p_{n_a}(x)|_{U_a} = p_{n0} \left[ \exp \frac{e(U_0 + U_a e^{i\omega t})}{kT} - 1 \right] e^{-\frac{x}{L_p}} - p_{n0} \left[ \exp \frac{eU_0}{kT} - 1 \right] e^{-\frac{x}{L_p}} =$$

$$= p_{n0} e^{-\frac{x}{L_p}} \left[ \exp \frac{e(U_0 + U_a e^{i\omega t})}{kT} - 1 - \exp \frac{eU_0}{kT} + 1 \right] = p_{n0} \exp \frac{eU_0}{kT} e^{-\frac{x}{L_p}} \left[ \exp \frac{eU_a e^{i\omega t}}{kT} - 1 \right] =$$

only if  $U_a \ll \frac{kT}{e}$

$$\approx p_{n0} \exp \frac{eU_0}{kT} e^{-\frac{x}{L_p}} \frac{eU_a e^{i\omega t}}{kT} = p_{n0} \exp \frac{eU_0}{kT} \frac{eU_a}{kT} e^{-\frac{x}{L_p}} e^{i\omega t} = p_{n0} \exp \frac{eU_0}{kT} \frac{eU_a}{kT} e^{-\frac{x}{\lambda_p}}$$

when if  $\frac{L_p}{x} t = \tau_{capt, R}$

$$\lambda = \frac{L_p}{\sqrt{1 + i\omega \tau_{capt, R}}}$$

$$j_p|_{U_0} = -eD_p \frac{\partial p_n|_{U_0}}{\partial x} = eD_p \left[ \exp \left( \frac{eU_0}{kT} \right) - 1 \right]$$

$$Y = \frac{j_p}{U_{ac}} = \frac{e}{kT} (j_p + j_{p,dif}) \sqrt{1 + i\omega \tau_{capt, R}} = G + i\omega B = \frac{1}{R_{depl}} + i\omega C_b$$

$$j_p|_{U_{ac}} = -eD_p \frac{\partial \Delta p_n|_{U_{ac}}}{\partial x} \cong \frac{eU_{ac}}{kT} (j_p + j_{p,dif}) \sqrt{1 + i\omega \tau_{capt, R}}$$